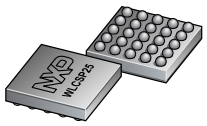


SOT1397-7

WLCSP25, wafer level chip-scale package; 25 bumps; 0.4 mm pitch, 2.09 mm x 2.09 mm x 0.525 mm body

10 January 2018 **Package information**

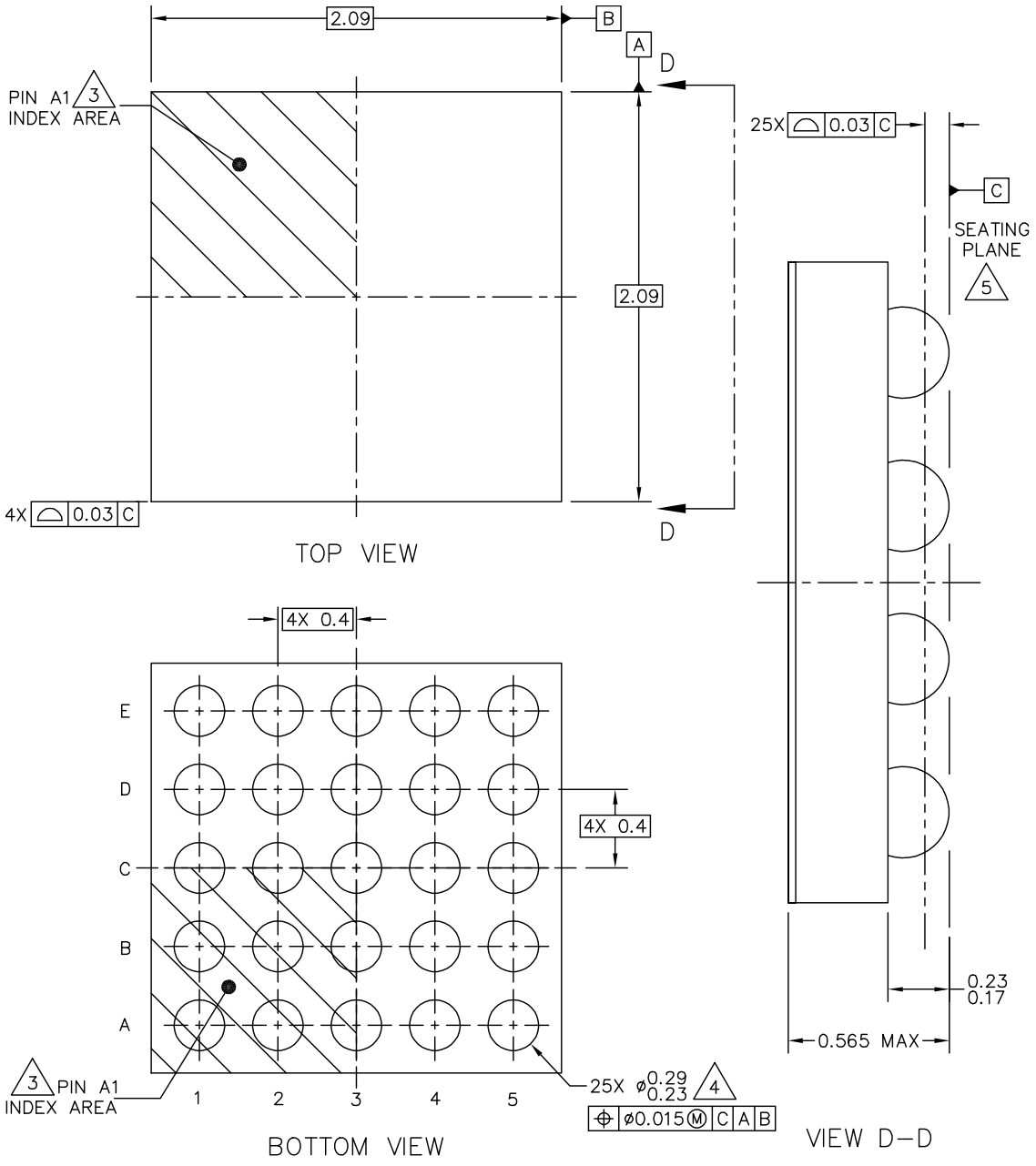
1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP25
Package type industry code	WLCSP25
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	4-12-2017
Manufacturer package code	98ASA01151D

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		-	-	2.09	-	mm
E	package width		-	-	2.09	-	mm
A	seated height		-	-	0.525	-	mm
e	nominal pitch		-	-	0.4	-	mm
n_2	actual quantity of termination		-	-	25	-	A/A

2. Package outline



DATE: 04 DEC 2017

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: SOT1397-7	REVISION: 0	

Fig. 1. Package outline WLCSP25 (SOT1397-7)

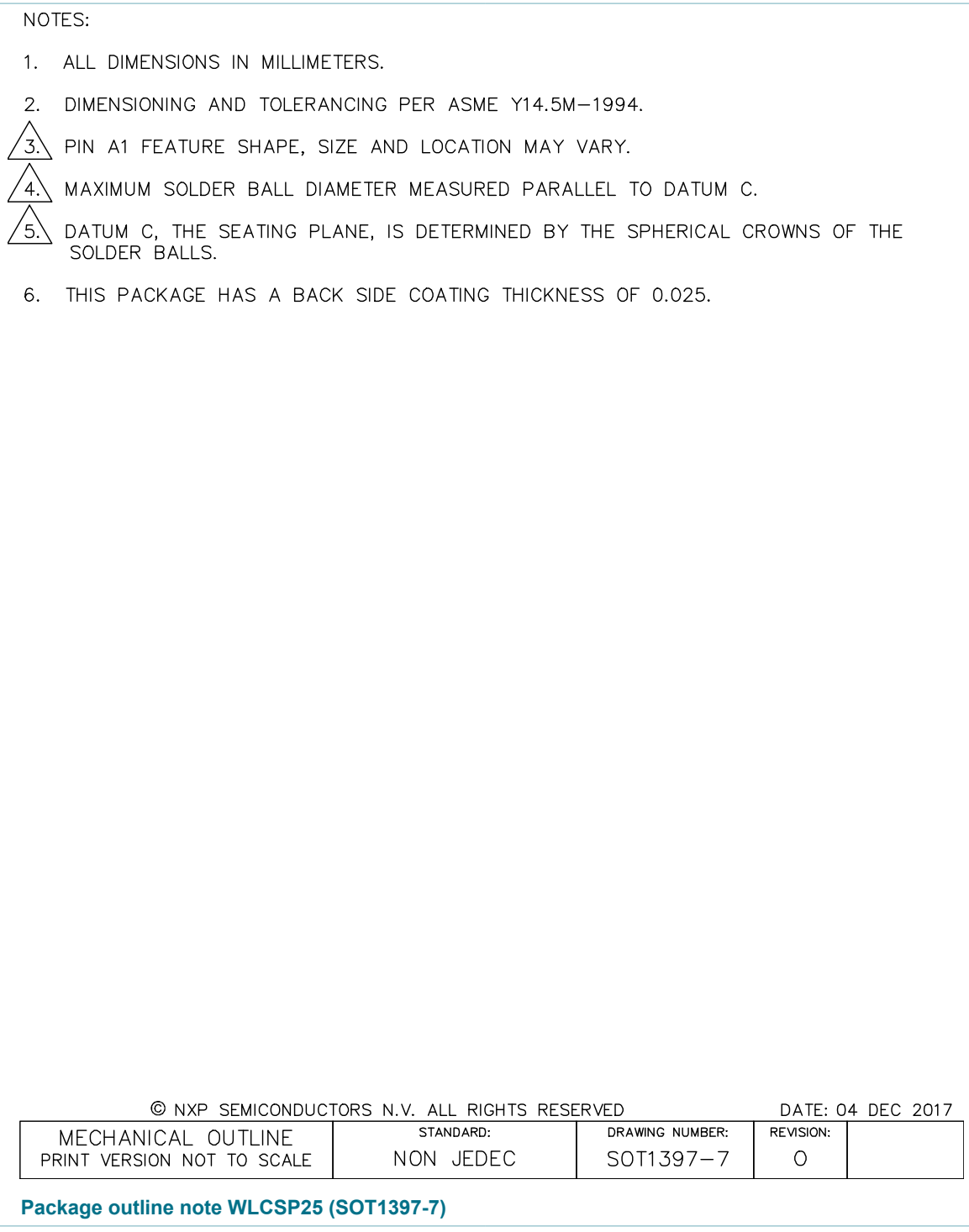


Fig. 2. Package outline note WLCSP25 (SOT1397-7)

3. Soldering

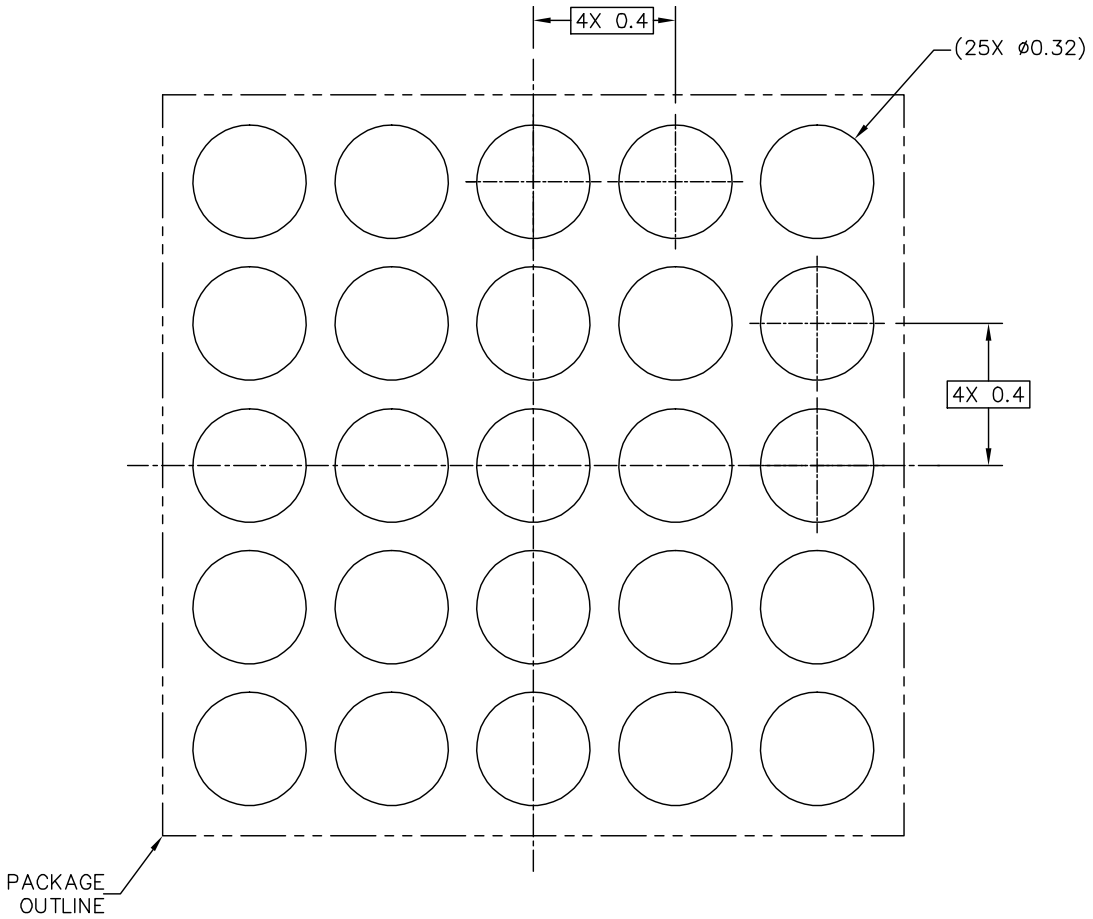


Fig. 3. Reflow soldering footprint for WLCSP25 (SOT1397-7)

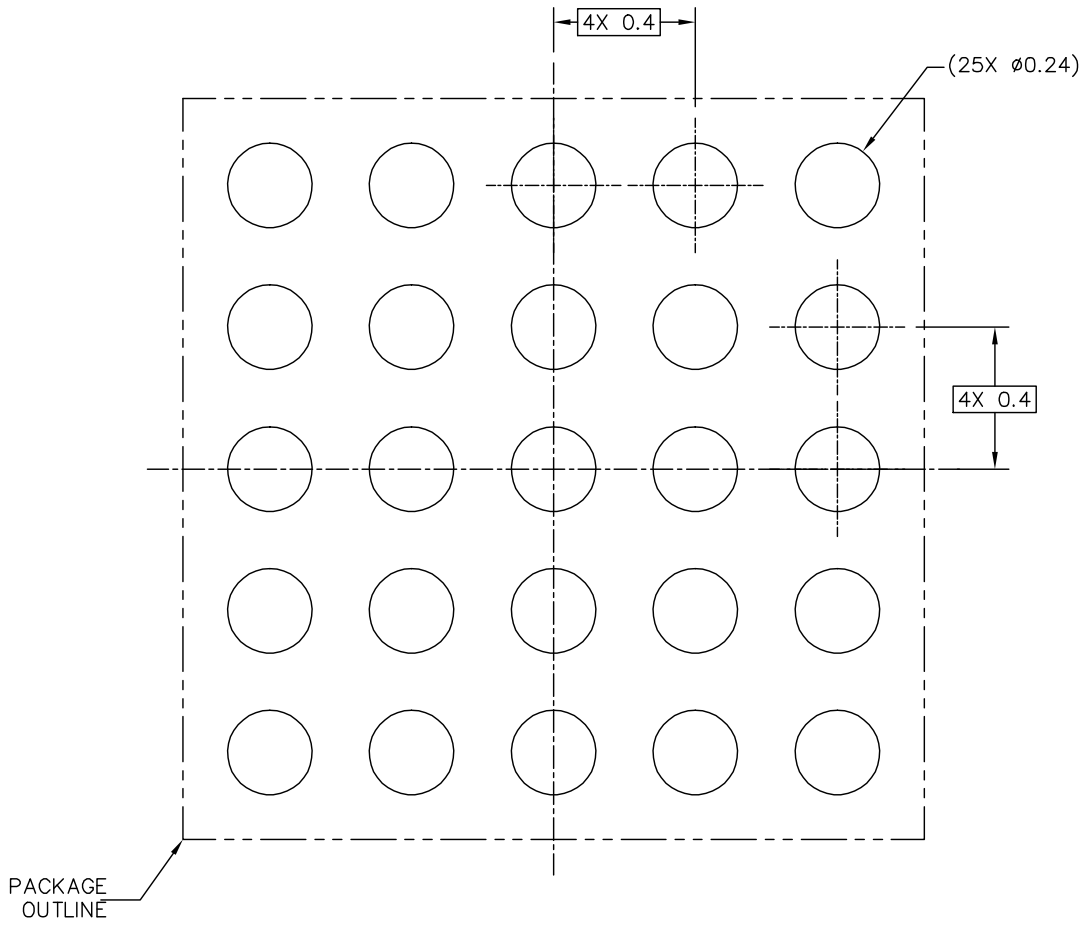


Fig. 4. Reflow soldering footprint part2 for WLCSP25 (SOT1397-7)

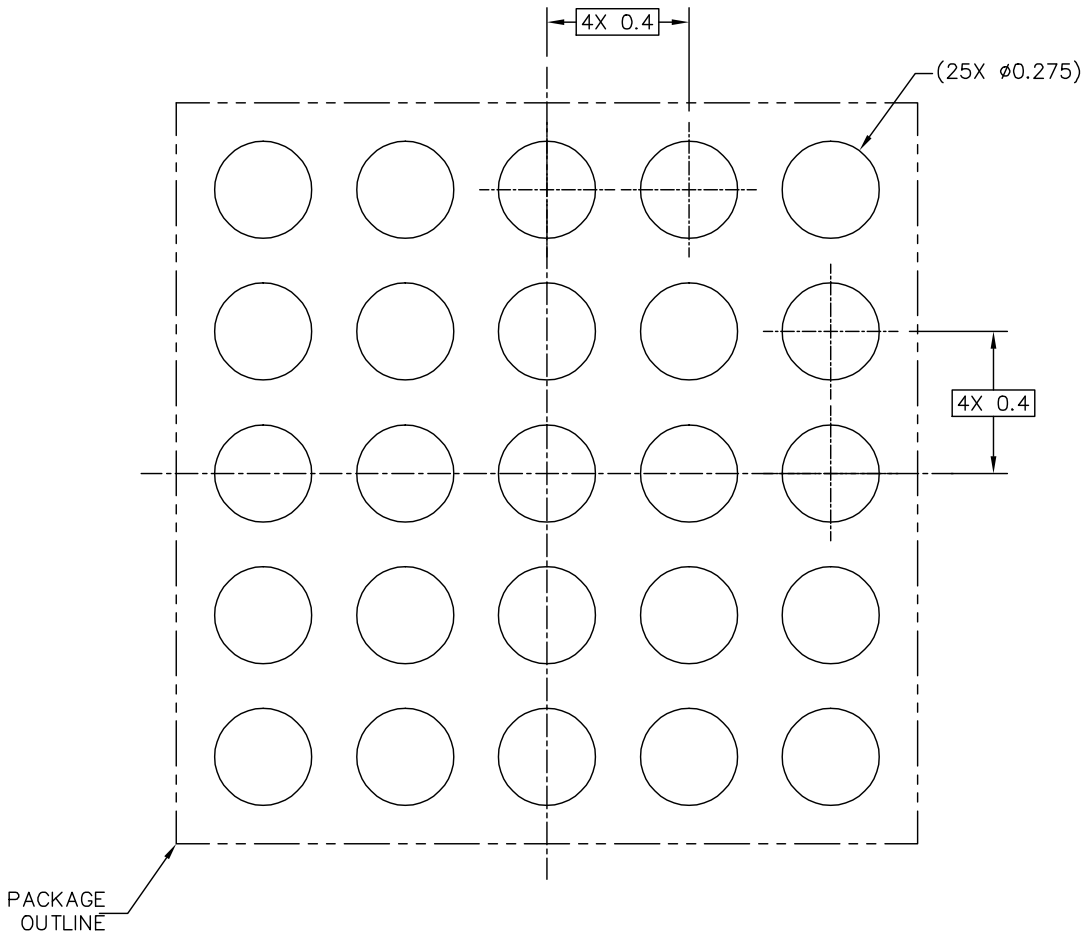


Fig. 5. Reflow soldering footprint part3 for WLCSP25 (SOT1397-7)

4. Legal information

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5. Contents

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Date of release: 10 January 2018